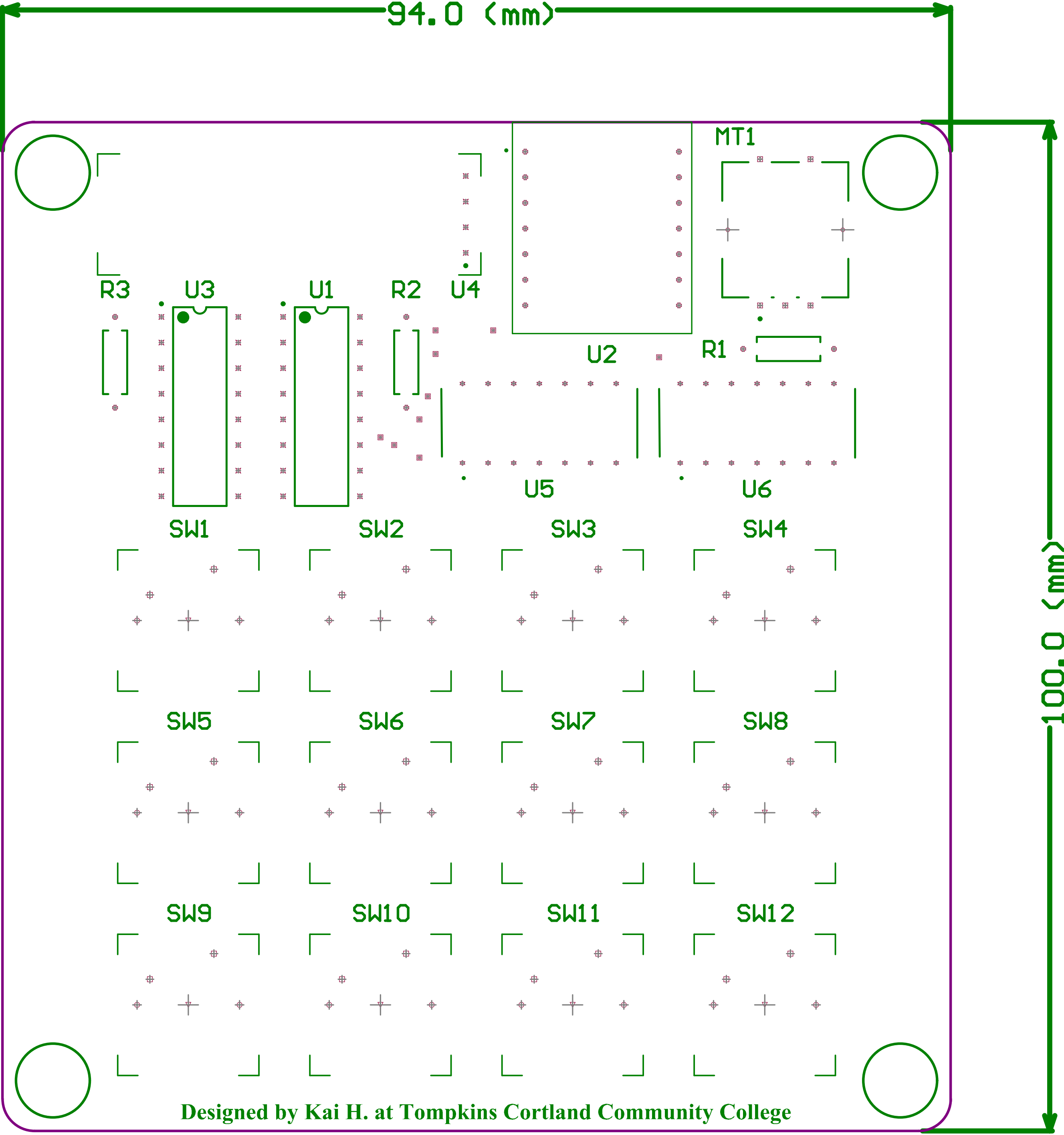


Layer	Name	Material	Thickness	Constant	Rigid
	Top Overlay				
	Top Solder	Solder Resist	0.013mm	3.3	
1	Top Layer		0.018mm		
	Dielectric1	FR-4	1.499mm	4.3	
2	Bottom Layer		0.018mm		
	Bottom Solder	Solder Resist	0.013mm	3.3	
	Bottom Overlay				



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
■	9	0.254mm (10.00mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
☆	28	0.770mm (30.32mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
⊕	20	0.850mm (33.47mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
✕	36	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
⊗	5	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
□	24	1.524mm (60.00mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
○	24	1.700mm (66.93mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
▽	12	4.000mm (157.48mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
◇	2	4.400mm (173.23mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded Rectangle
	160 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Rigid
	Top Overlay				
	Top Solder	Solder Resist	0.013mm	3.3	
1	Top Layer		0.018mm		
	Dielectric1	FR-4	1.499mm	4.3	
2	Bottom Layer		0.018mm		
	Bottom Solder	Solder Resist	0.013mm	3.3	
	Bottom Overlay				